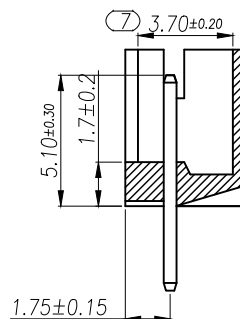
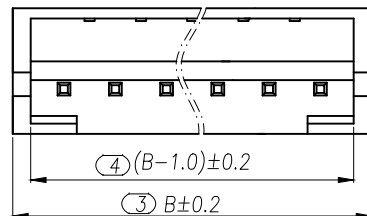
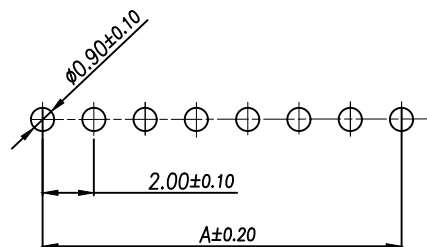
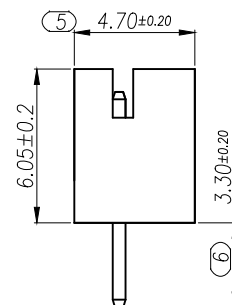
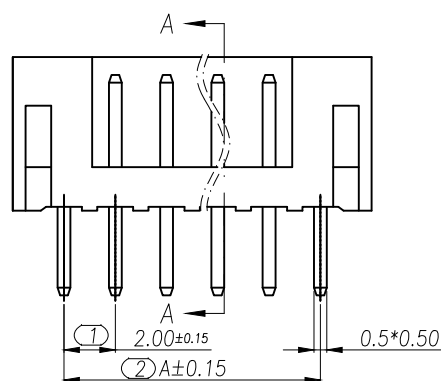


PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

Part No	PIN	A	B
XY-S2B-PH-K	2	2	6
XY-S3B-PH-K	3	4	8
XY-S4B-PH-K	4	6	10
XY-S5B-PH-K	5	8	12
XY-S6B-PH-K	6	10	14
XY-S7B-PH-K	7	12	16
XY-S8B-PH-K	8	14	18
XY-S9B-PH-K	9	16	20
XY-S10B-PH-K	10	18	22
XY-S11B-PH-K	11	20	24
XY-S12B-PH-K	12	22	26
XY-S13B-PH-K	13	24	28
.....	...	...	...
XY-S20B-PH-K	20	(20-1)*2	(20+1)*2

技术要求:

1. 塑件材料: PA66 (UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 1000M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim +85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $220^{\circ}\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和铜等六大有害物质含量要符合环保要求

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyeconn Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.35	X.*± 5°	APR. Alex	TITLE: WAFER 2.0mm H6.0mm 180° DIP		
.XX±0.25	.X.*± 3°	CHK. Jack	DWG NO. XY-SNB-PH-K		
.XXX±0.15	.XX.*± 1°	DRA. Can	PROJ. 		CUSTOMER DRAWING
			SIZE A4	SCALE 1:1	SHEET 1 / 1